

REMARKS

The Office Action dated January 5, 2007 has been received and carefully reviewed. The preceding amendments and the following remarks form a full and complete response thereto. Claims 7-9 have been cancelled without prejudice or disclaimer. New claims 10-13 have been added. No new matter is added. Accordingly, claims 10-13 are pending in this application and are submitted for consideration.

An objection was made to the Abstract on the ground that it contained two paragraphs. The Abstract has been rewritten in one paragraph. Accordingly, the Applicant requests that the objection be withdrawn.

Claims 7-9 were rejected under 35 U.S.C. § 112, second paragraph, as being allegedly indefinite. The rejections are moot in view of the cancellation of claims 7-9. The Applicant submits that new claims 10-13 comply with the requirements of 35 U.S.C. § 112.

Claims 7-8 were rejected under 35 U.S.C. § 102(b) as allegedly being anticipated by U.S. Patent No. 4,653,362 to Gerber. Claim 9 was rejected under 35 U.S.C. § 103(a) as allegedly being unpatentable over Gerber. The rejections are moot because claims 7-9 have been cancelled without prejudice or disclaimer.

The Applicant submits that new claims 10-13 recite subject matter not disclosed or suggested by Gerber. Claim 10, upon which claims 11-12 depend, defines a method of cutting sheet members that includes a step of locally heating a seam allowance or a region outside the seam allowance and, by the local heating, welding the upper and lower sheet members together. Thus, sheet members are welded before cutting. Gerber fails to disclose the claimed method and, in fact, teaches away from these claimed features. In

particular, in column 8, lines 15-18, Gerber discloses that if pattern pieces are beginning to fuse to each other, the heat output is lowered. Thus, Gerber teaches away from the combination of welding the sheet members and then cutting the members.

Claim 13 is directed to method for cutting sheet members that includes a combination of steps of cutting the sheet members having uncut portions and then cutting only the uncut portions. Gerber fails to disclose or suggest the features of claim 13.

In view of the above, all objections and rejections have been sufficiently addressed. The Applicant submits that the application is now in condition for allowance and requests that claims 10-13 be allowed and this application passed to issue.

The Examiner requested that foreign references cited on the IDS June 29, 2005 have not been received from the International Bureau and requested that the Applicant provide copies. Copies of the Japanese patent abstracts for JP 63-100602 and JP 7-112081 are provided. With respect to JP 8-9211, JP 03045336 A corresponds thereto. Further, the Applicant directs the Examiner to U.S. Patent 5,087,236, which is in the same patent family as JP 8-9211.

In the event that this paper is not timely filed, Applicant respectfully petitions for an appropriate extension of time. Any fees for such an extension together with any additional fees maybe charged to Deposit Account No. 02-2135.

If for any reason the Examiner determines that the application is not now in condition for allowance, it is respectfully requested that the Examiner contact, by telephone, the Applicant's undersigned attorney at the indicated telephone number to arrange for an interview to expedite the disposition of this application.

Respectfully submitted,

By



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JAPANESE PATENT OFFICE

PATENT ABSTRACTS OF JAPAN

(11) Publication number: 63100602 A
(43) Date of publication of application: 02.05.1988

(51) Int. Cl G11B 5/127

(21) Application number: 61245897

(71) Applicant: SANYO ELECTRIC CO LTD

(22) Date of filing: 16.10.1986

(72) Inventor: OGAWA TAKAHIRO

(54) MANUFACTURE OF MAGNETIC HEAD

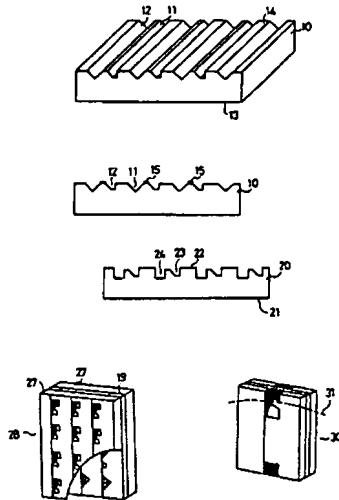
(57) Abstract:

PURPOSE: To efficiently perform a junction process and to eliminate a chip dislocation trouble by sandwiching a 'Sendust(R)' chip compound material with a reinforced core compound material.

CONSTITUTION: After a winding groove 11 and a silver solder charging groove 12 are provided at a 'Sendust(R)' wafer 10, a rear surface 13 and a front surface 14 of the wafer 10 are mirror-ground with high accuracy, an SiO_2 film is formed at the front gap part of the wafer 10 as a gap spacer 15. After plural wafers 10 are accumulated, welding is executed with a silver solder and two wafers 10 are firmly combined. The welding wafer is sliced by giving an azimuth angle, plural 'Sendust(R)' chip compound materials 19 are obtained and the compound materials 19 is thickness-processed up to a desired track width. On the other hand, in the same way concerning a reinforced core compound material, a winding groove 23 and a glass charging groove 24 are formed, plural ferrite wafers 20 are accumulated, and thereafter, welding and combin-

ing are executed by a glass. By two reinforced core compound materials, the compound materials 19 are sandwiched, the coalesce is cut and a head chip 30 is obtained.

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JAPANESE PATENT OFFICE

PATENT ABSTRACTS OF JAPAN

(11) Publication number: 07112081 A
(43) Date of publication of application: 02.05.1995

(51) Int. Cl B26B 27/00
B26D 1/02, B43M 7/00

(21) Application number: 05284384
(22) Date of filing: 18.10.1993

(71) Applicant: KYUSHU HITACHI MAXELL LTD
(72) Inventor: TERAYAMA MASAYA

(54) SHEET-LIKE BODY CUTTING DEVICE

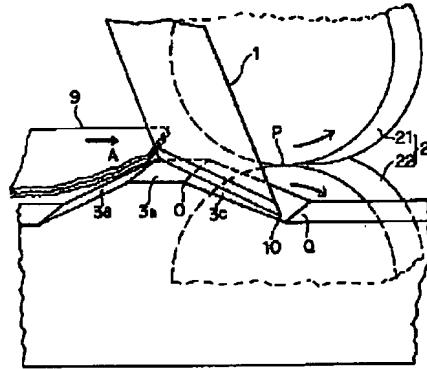
(57) Abstract:

PURPOSE: To provide the paper cutting device by which chips are not generated after cutting, and a smooth and permanent cutting quality is obtained, with regard to the paper cutting device for cutting plural sheets of paper, and especially, with regard to the paper cutting device used for opening an envelope, etc.

CONSTITUTION: This device is constituted so that an envelope 9 is carried to the side by two rollers 21, 22 of an envelope carrying part 2, this carried envelope 9 is guided to the direction in which projecting parts 3 (3a-3c) cross against the carrying direction, and this guided envelope 9 is cut by a cutting part 1 projected so as to be opposed to the projecting parts 3. This cutting part 1 advances and executes cutting successively from the paper of the upper-most layer to the

lower layer side, and only the paper of the lowest layer moves backward to a cavity part Q formed on the side of the projecting parts 3 and is left uncut, and it is prevented that chips after cutting are cut off by the paper of the lowest layer.

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JAPANESE PATENT OFFICE

PATENT ABSTRACTS OF JAPAN

(11) Publication number: 03045336 A
(43) Date of publication of application: 26.02.1991

(51) Int. Cl B31B 1/20
B26F 1/00

(21) Application number: 01181463
(22) Date of filing: 13.07.1989

(71) Applicant: MORIMOTO HIDEO
(72) Inventor: MORIMOTO HIDEO

(54) SEPARATING DEVICE OF BLANK PART FROM SCRAP PART

(57) Abstract:

PURPOSE: To easily perform paper feeding operation in a short time by a structure wherein a liner, which slidably shuttles between a die cutting section and a paper feeding section, and is equipped with a bottom force supporting stand, a front gauge provided on the bottom force supporting stand and a slide plate and guide plates, both of which are installed in the paper feeding section are provided.

CONSTITUTION: Fitting molds, which are fixed to the bottom force supporting stand 19 on a liner 18 at a paper feeding section 31, are conveyed to a die cutting section 32 by driving the liner 18. After that, after a top force supporting stand 22 is brought close to the fitting molds so as to magnetically attract male molds 7 and 8, the liner 18 is brought back to its initial position. Next, under the condition that a slide plate 37 is brought to the top surface of the bottom force supporting stand 19 of the liner and the guide plates 36 at the sides of the slide plate and a front gauge 35 at the tip of the bottom force supporting stand 19 are brought into the state to be normal to each other, base papers

M are placed on the slide plate 37 so as to be squared to the front gauge 35 and the guide plates 36. After that, by driving the timer 18 under the condition that the base papers are pushed against the front gauge 35, the distance between the slide plate 37 and the front gauge 35 becomes larger, resulting in placing the base papers M from on the slide plate to on the bottom force in order to convey to the die cutting section 30.

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